

TECHNICAL DATASHEET

1 MIL POLYIMIDE FILM SILICONE ADHESIVE

DESCRIPTION

Manufactured from 1 mil thin polyimide film with 1.5 mils high performance silicone adhesive.

PRODUCT BENEFITS

It is chosen for protecting gold finger of PCB during wave soldering process.

- Safe and clean removal from PCB.
- High conformability

Item	Test Method	Normal	Min.
Adhesive		Silicone	
Backing		Polyimide Film	
Carrier Thickness (mil/mm)	ASTM D 1000	1.00 / 0.025	
Total Thickness (mil/mm)	ASTM D 1000	2.20 / 0.055	2.08 / 0.052
Color		Amber	
Adhesion to Steel (N/25mm)/(g/25mm)/(oz/in)	ASTM D 1000	6.3 / 650 / 22.8	5.4 / 550 / 19.4
Tensile Strength (N/25mm)/(kg/25mm)/(lb/in)	ASTM D 1000	108 / 11 / 24	88 / 9.0 / 20
Dielectric Strength (kV)	ASTM D 149	5.5	5.0
Unwind Force (N/25mm)/(kg/25mm)/(oz/in)		4.9 / 500 / 17.6 3.4 / 350 / 12.3	
Class of Insulation (°C)	UL 510	UL H / 200	
Elongation (%)	ASTM D 1000	80	60
Range of Temperature (C/F)		-73 ~ 260 / -100 ~ 500	

The above values are typical values and should be used only as a guide. Due to the nature of process variables, Echo makes no warranty or guarantee on the use of this product in a specific process and user should always test material in their own process before running production.